



Product Change Notification / CENO-18MRDB845

Date:

22-Sep-2023

Product Category:

Switching Regulators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6490 Initial Notice: Qualification of Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site for Microsemi SG3526BDW, SG3526BDW-TR, SG3526BN, SG2526BDW, SG2526BDW-TR and SG2526BN catalog part numbers (CPN) available in 18L SOIC and PDIP (.300in) packages.

Affected CPNs:

[CENO-18MRDB845_Affected_CPN_09222023.pdf](#)

[CENO-18MRDB845_Affected_CPN_09222023.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site for Microsemi SG3526BDW, SG3526BDW-TR, SG3526BN, SG2526BDW, SG2526BDW-TR and SG2526BN catalog part numbers (CPN) available in 18L SOIC and PDIP (.300in) packages.

Pre and Post Change Summary:

	Pre Change	Post Change
Fabrication Site	Microsemi Garden Grove Bipolar Linear Fab Line Fab1 (MGGV)	Microchip Technology Tempe – Fab 2 (TMGR)
Wafer diameter	4 inches	8 inches
Die size	No change	No change

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability and on-time delivery performance by qualifying Microchip Technology Tempe – Fab 2 (TMGR) as a new fabrication site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:March 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2023					>	March 2024				
Workweek	3 5	3 6	3 7	3 8	3 9		9	1 0	1 1	1 2	1 3
Initial PCN Issue Date				x							
Qual Report Availability											x
Final PCN Issue Date											x

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:September 22, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_CENO-18MRDB845_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

SG3526BDW

SG3526BN

SG2526BDW

SG2526BN

SG2526BDW-TR

SG3526BDW-TR